CLAIMS

What is claimed is:

1. A method of creating a conductive path between two or more conductive layers, wherein the conductive layers are separated by one or more dielectric layers, the method comprising:

exposing portions of at least two conductive layers;

applying a conductive material to the exposed portions of the conductive layers, the conductive material creating an electrical coupling between the conductive layers; and

grounding at least one of the conductive layers to a controlled ground potential.

2. A method as recited in claim 1, wherein the portions of the conductive layers are exposed by recessing at least one of the conductive layers and any dielectric layers positioned between the conductive layers, the conductive material overhanging an uppermost of the conductive layers.

3. A method as recited in claim 2, wherein a material of one or more of the conductive layers is copper and a material of one or more of the conductive layers is stainless steel.

4. A method as recited in claim 2, wherein the conductive material is selected from a group consisting of solder and a conductive adhesive.

5. A method as recited in claim 2, wherein one or more of the conductive layers is grounded to a controlled ground potential using one or more dedicated ground paths etched from one or more of the conductive layers.

6. A method as recited in claim 1, wherein the exposed portion of at least one of the conductive layers includes a through-hole, where the conductive material is a rivet extending through the through hole.

7. A method as recited in claim 6, wherein the rivet creates a grounding path between a top grounded layer and one or more of the underlying conductive layers.

8. A method as recited in claim 6, wherein a material of one or more of the conductive layers is copper and a material of one or more of the conductive layers is stainless steel.

9. A method as recited in claim 6, wherein one or more of the conductive layers is grounded to a controlled ground potential using one or more dedicated ground paths etched from one or more of the conductive layers.

10. A method as recited in claim 1, wherein the conductive material is a finger formed by etching, the finger extending from an uppermost of the conductive layers and pressed onto the exposed portion of an underlying conductive layer.

11. A method as recited in claim 10, wherein a material of one or more of the conductive layers is copper and a material of one or more of the conductive layers is stainless steel.

12. A method as recited in claim 10, wherein one or more of the conductive layers is grounded to a controlled ground potential using one or more dedicated ground paths etched from one or more of the conductive layers.

13. A method as recited in claim 10, wherein the finger is welded and place.

14. A method as recited in claim 1, wherein the conductive material is a finger formed by etching, the finger being sandwiched between a mount plate and an arm.

15. A method as recited in claim 14, wherein a material of one or more of the conductive layers is copper and a material of one or more of the conductive layers is stainless steel.

16. A method as recited in claim 14, wherein one or more of the conductive layers is grounded to a controlled ground potential using one or more dedicated ground paths etched from one or more of the conductive layers.

17. A method as recited in claim 14, wherein the finger is welded in place.

18. A method as recited in claim 1, wherein the conductive material is a finger formed by etching, the finger being sandwiched between a mount plate and a load beam.

19. A method as recited in claim 18, wherein a material of one or more of the conductive layers is copper and a material of one or more of the conductive layers is stainless steel.

20. A method as recited in claim 18, wherein one or more of the conductive layers is grounded to a controlled ground potential using one or more dedicated ground paths etched from one or more of the conductive layers.

21. A method as recited in claim 18, wherein the finger is welded in place.

22. A method as recited in claim 1, further comprising an extraneous conductive layer, the conductive material being a dimple extending from the extraneous conductive layer and contacting the exposed portions of the conductive layers.

23. A method as recited in claim 22, wherein the dimple extends through a via in at least one of the conductive layers.

24. A method as recited in claim 22, wherein a material of one or more of the conductive layers is copper and a material of one or more of the conductive layers is stainless steel.

25. A method as recited in claim 22, wherein one or more of the conductive layers is grounded to a controlled ground potential using one or more dedicated ground paths etched from one or more of the conductive layers.

26. A method as recited in claim 1, wherein the portions of the conductive layers are exposed by punching a

hole through the conductive layers, the conductive material extending through the hole.

27. A method as recited in claim 26, wherein a material of one or more of the conductive layers is copper and a material of one or more of the conductive layers is stainless steel.

28. A method as recited in claim 26, wherein one or more of the conductive layers is grounded to a controlled ground potential using one or more dedicated ground paths etched from one or more of the conductive layers.